

# STENCILCLEAN SIA

## Spray in air System for cleaning of metal stencils

STENCILCLEAN SIA extends the range of PBT cleaning machines for "SMT assembly". It is intended for the cleaning of metal stencil foils or frames up to 29" x 32" contaminated with solder cream or glue. It can also be used for the first phase of Misprints and PCB cleaning, where ionic contamination cleaning requirements (DI Water Rinse) must be carried out outside of the machine.

STENCILCLEAN SIA has an extremely high performance to price ratio. The special design is very safe for the cleaning of both PumpPrint® stencils with glue right through to very thin (< 100 microns) stencils.



### Basic features of the system

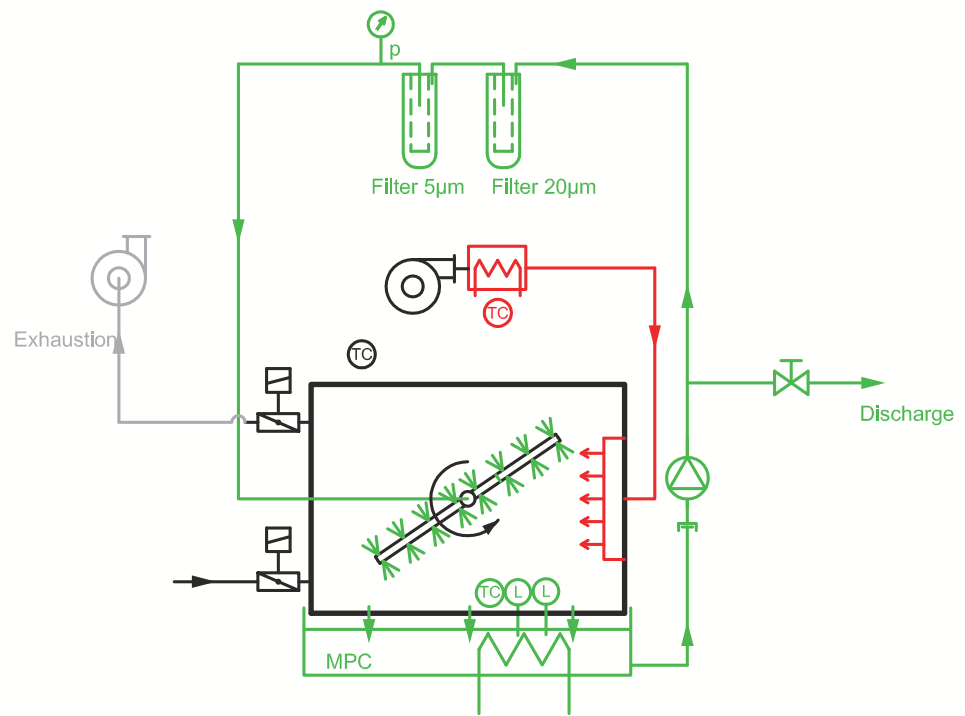
- The machine is designed to work with water based chemicals.
- It can work with other chemicals with good rinsing ability.
- All stainless steel design of frame, chamber and shielding.
- Process chamber with motoric driven rotating manifolds.
- High-pressure / high volume system assures high quality and fast cleaning. Totally ballanced spray impact from both sides of the stencil prevents stencil damage by lowering mesh tension between frame and stencil sheet, which occurs frequently at spray systems with non-coordinated movement of spray arms.
- During the spray process, the chamber is completely closed to reduce the loss of cleaning liquid.
- Chamber is equipped with a servo-valve on the air intake and exhaust opening which are controlled by software during the drying process.
- Exhaust port to be connected to external exhaust system.
- The machine has four casters for easy transport and maintenance.
- Three-stage cleaning of the cleaning medium (decanter + two-stage filtration with 20 + 5 micron filters) allows effective use of a proportion of cleaning medium for the rinsing process.
- Drying process with hot air and programmable temperature and exhausting.
- Control system (microprocessor with 10 prog. recipies).
- Controlled parameters
  - cleaning time
  - cleaning temperature
  - drying time
  - drying time with hot air
- Temperature of drying process.
- Cleaning liquid level monitoring.
- Filter status monitoring.

## Process chamber

- Balanced rotating manifolds from both sides are electrically driven simultaneously therefore preventing damage of stencils or foils due to bending strain and / or cupping.

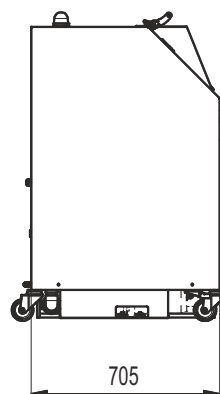
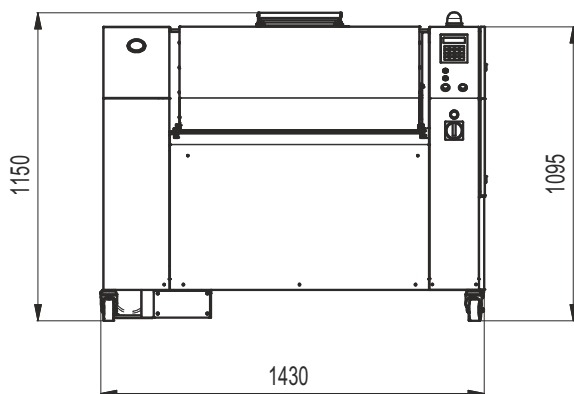


## Process diagram



## Technical data

Maximal size of the cleaned stencil	LxWxH	740 x 820 x 90 mm
Cleaning agent volume		70 litres
Heating temperature	cleaning	max. 50 °C
	drying	max. 90 °C
Typical cycle times (depends on application)		washing: 5-10 min / drying: 5-15 min
Software versions		English, German, Czech (other on request)
Mains power supply; protection; plug		400V, 50Hz (3P + N + PE); 32 A; EU 32 A
Installed power		12 kVA
Power consumption during operation (average)		4 kW
Exhaust capacity; port diameter		200 m <sup>3</sup> /hr; 90 mm
Weight of empty machine		170 kg



## PBT local distributor